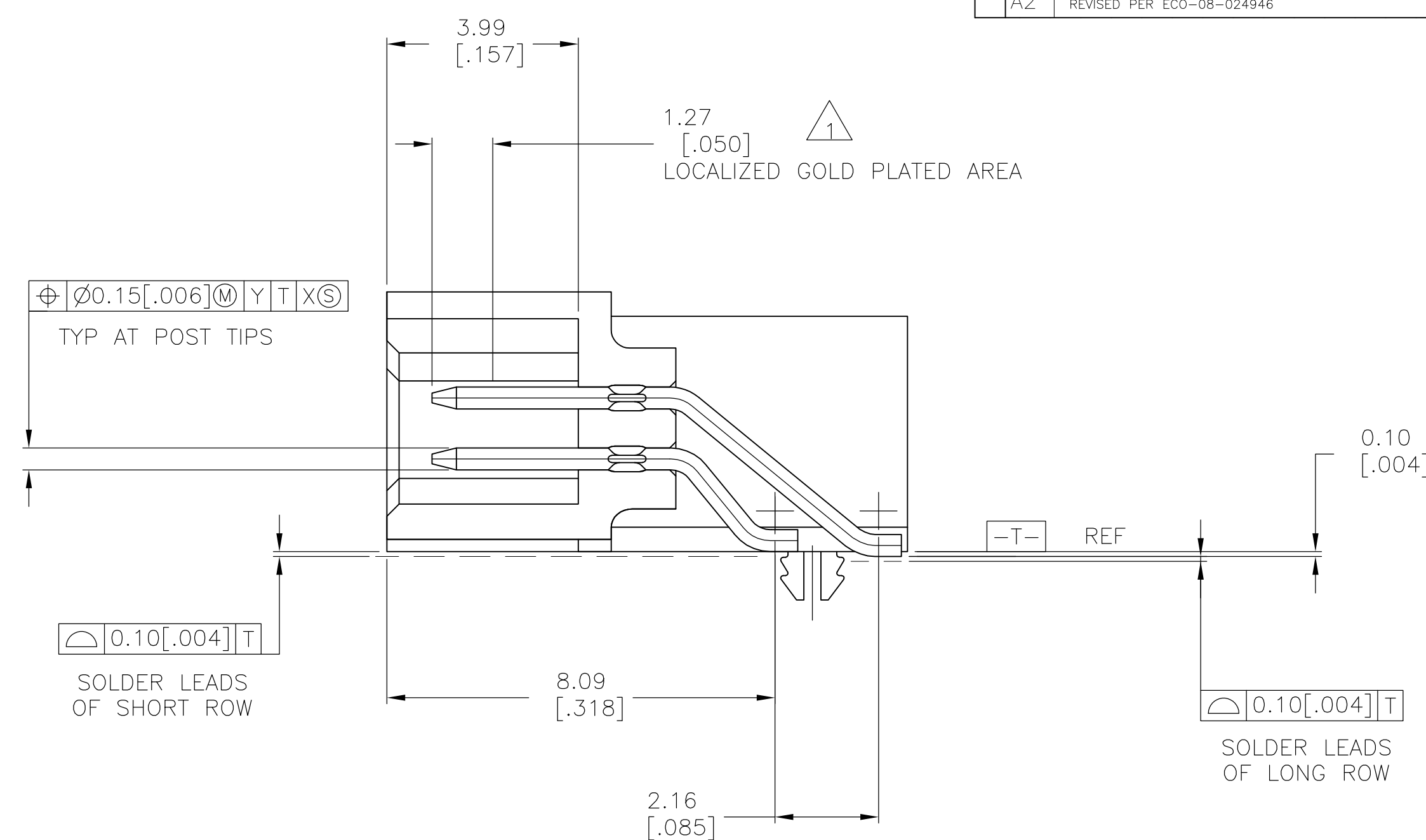
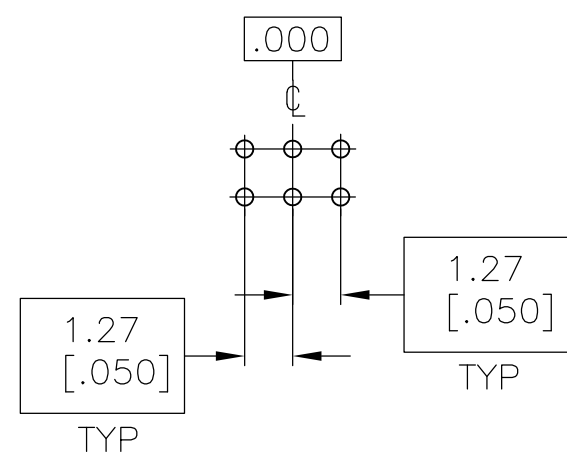
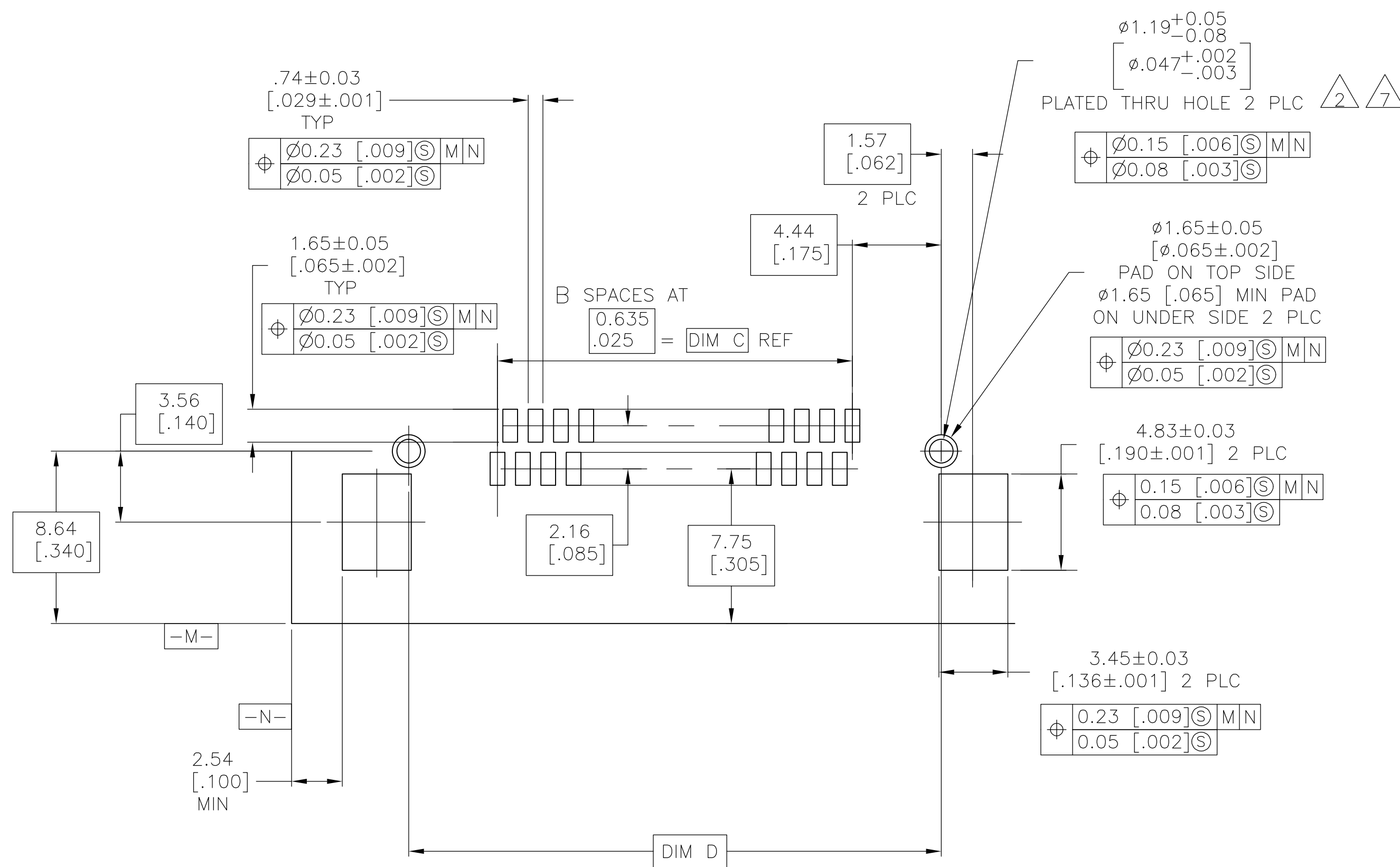




1. 0.00076 [.000030] GOLD IN LOCALIZED PLATE AREA
0.00381 [.000150] TIN-LEAD ON SOLDER LEADS
ALL OVER 0.00127 [.000050] NICKEL
2. USE 1.32±0.02 [.0520±.0010] DRILLED HOLE (#55 DRILL)
FINISH TO BE TIN-LEAD OVER 0.02 [.001] MIN COPPER
3. PLATING: 0.0038 [.000150] TIN-LEAD OVER 0.00127 [.000050] NICKEL
4. SERRATIONS OPTIONAL THIS SURFACE.
6. PLATING: 0.0038 (.00015) TIN OVER .00127 (.000050) NICKEL.
7. USE 1.32+/-0.02 (.052+/- .0010) DRILLED HOLE (#55 DRILL)
FINISH TO BE TIN OVER 0.02 (.001) MIN COPPER



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